

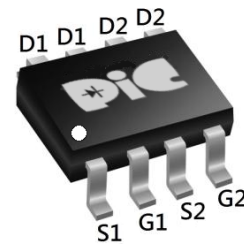
### ➤ General Description

This PAC69TJ03J N&P Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent  $R_{ds(On)}$  performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

### ➤ Feature

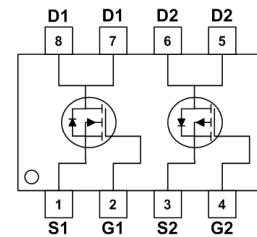
- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent  $CdV/dt$  effect decline
- Advanced high cell density Trench technology

### ➤ SOP-8



### ➤ Application

- Notebook CPU Core-High-Side Switch



### ➤ Absolute Maximum Ratings

Parameter	Symbol	Rating		Units
		N-Channel	P-Channel	
Drain-Source Voltage	$V_{DS}$	60	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_A=25^\circ C$	5	-3.8	A
Continuous Drain Current, $V_{GS} @ 10V_1$	$I_D @ T_A=70^\circ C$	4	-3.2	A
Pulsed Drain Current <sup>2</sup>	$I_{DM}$	20	-14	A
Single Pulse Avalanche Energy <sup>3</sup>	EAS	22	28.8	mJ
Avalanche Current	$I_{AS}$	21	-24	A
Total Power Dissipation <sup>4</sup>	$P_D @ T_A=25^\circ C$	2	2	W
Storage Temperature Range	$T_{STG}$	-55 to 150	-55 to 150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to 150	-55 to 150	$^\circ C$
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	85		$^\circ C/W$
Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10sec$ )		62.5		$^\circ C/W$

### ➤ N-Channel Electrical Characteristics (T<sub>J</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	60	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5A	---	38	52	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	---	55	75	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0	---	2.5	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =4A	---	28	---	S
Total Gate Charge (4.5V)	Q <sub>g</sub>	V <sub>DS</sub> =48V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A	---	19	---	nC
Gate-Source Charge	Q <sub>gs</sub>		---	2.6	---	
Gate-Drain Charge	Q <sub>gd</sub>		---	4.1	---	
Turn-On Delay Time	T <sub>d(on)</sub>	V <sub>DD</sub> =30V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =4A	---	3	---	ns
Rise Time	T <sub>r</sub>		---	34	---	
Turn-Off Delay Time	T <sub>d(off)</sub>		---	23	---	
Fall Time	T <sub>f</sub>		---	6	---	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	1027	---	pF
Output Capacitance	C <sub>oss</sub>		---	65	---	
Reverse Transfer Capacitance	C <sub>rss</sub>		---	46	---	

### ➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current <sup>1,5</sup>	I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	2.5	A
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V

Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.1mH, I<sub>AS</sub>=21A
- 4.Ensure that the channel temperature does not exceed 150°C.
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

### ➤ P-Channel Electrical Characteristics (T<sub>J</sub>=25 C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-60	---	---	V
Static Drain-Source On-Resistance <sup>2</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-3.5A	---	80	100	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.1A	---	100	105	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	---	-2.5	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> =-5V, I <sub>D</sub> =-3A	---	8.5	---	S
Total Gate Charge (-4.5V)	Q <sub>g</sub>	V <sub>DS</sub> =-48V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3A	---	12.1	---	nC
Gate-Source Charge	Q <sub>gs</sub>		---	2.2	---	
Gate-Drain Charge	Q <sub>gd</sub>		---	6.3	---	
Turn-On Delay Time	T <sub>d(on)</sub>	V <sub>DD</sub> =-15V, V <sub>GS</sub> =-10V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-1A	---	9.2	---	ns
Rise Time	T <sub>r</sub>		---	20.1	---	
Turn-Off Delay Time	T <sub>d(off)</sub>		---	46.7	---	
Fall Time	T <sub>f</sub>		---	9.4	---	
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	---	1137	---	pF
Output Capacitance	C <sub>oss</sub>		---	76	---	
Reverse Transfer Capacitance	C <sub>riss</sub>		---	50	---	

### ➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current <sup>1,5</sup>	I <sub>S</sub>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	-2.5	A
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1A, T <sub>J</sub> =25°C	---	---	-1.2	V

Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=-25V, V<sub>GS</sub>=-10V, L=0.1mH, I<sub>AS</sub>=-24A
- 4.Ensure that the channel temperature does not exceed 150°C.
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

N-Ch and P-Ch Fast Switching MOSFET

$V_{DS}=60V$ ,  $I_D=5.0A$ ,  $R_{DS(ON)}=52m\Omega$

$V_{DS}=-60V$ ,  $I_D=-3.8A$ ,  $R_{DS(ON)}=100m\Omega$

## N-Channel Typical Characteristics

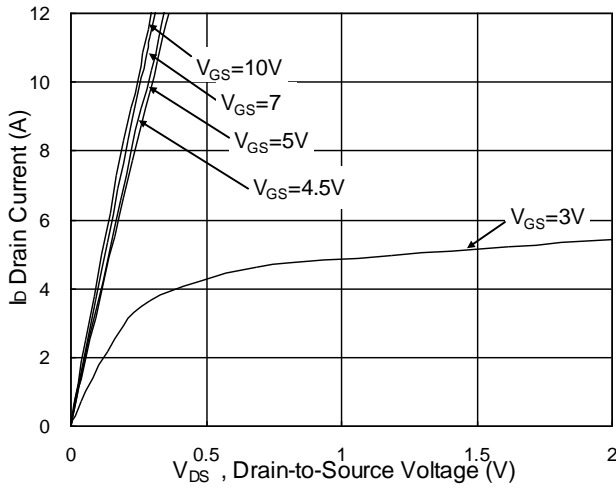


Fig.1 Typical Output Characteristics

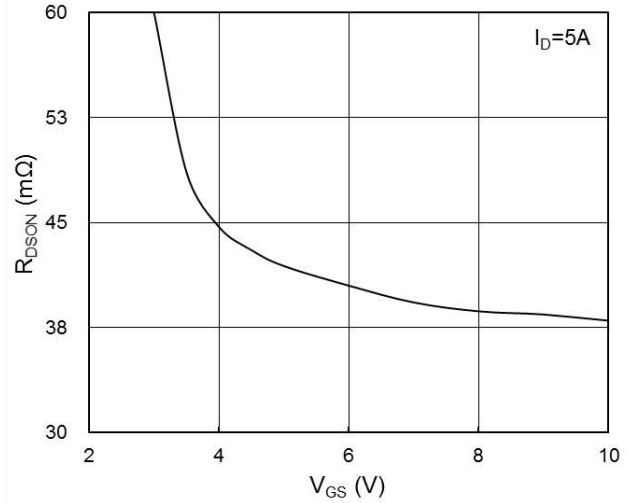


Fig.2 On-Resistance vs. G-S Voltage

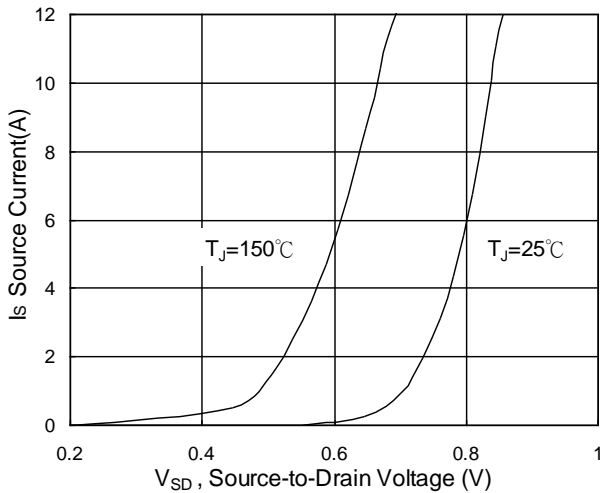


Fig.3 Source Drain Forward Characteristics

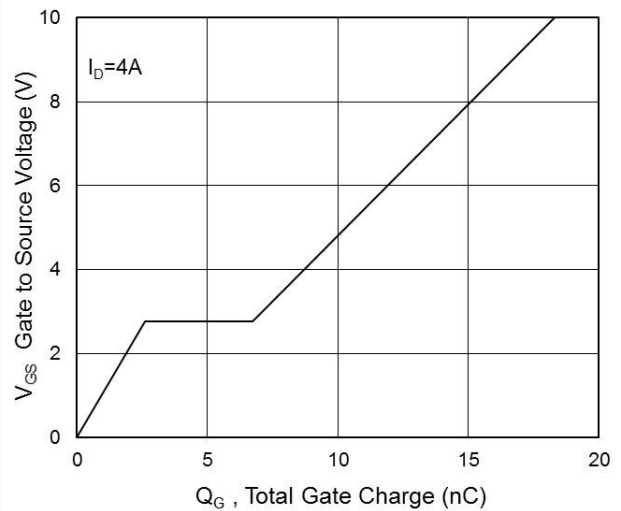


Fig.4 Gate-Charge Characteristics

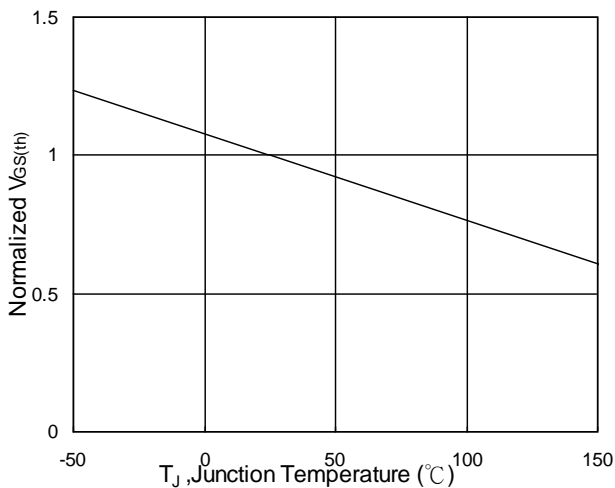


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

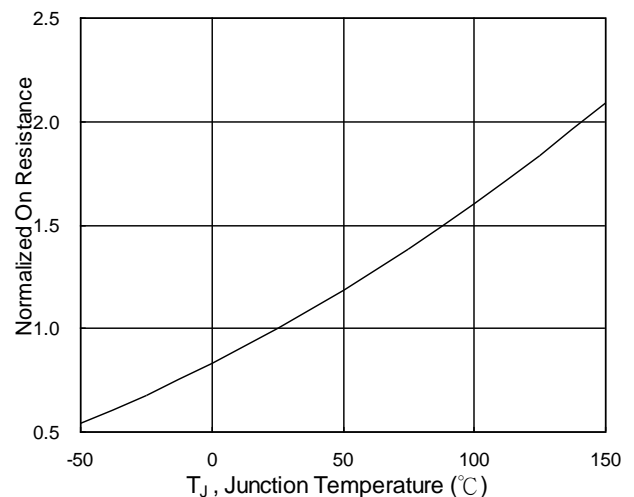


Fig.6 Normalized  $R_{DS(ON)}$  vs.  $T_J$

N-Ch and P-Ch Fast Switching MOSFET

$V_{DS}=60V, I_D=5.0A, R_{DS(ON)}=52m\Omega$

$V_{DS}=-60V, I_D=-3.8A, R_{DS(ON)}=100m\Omega$

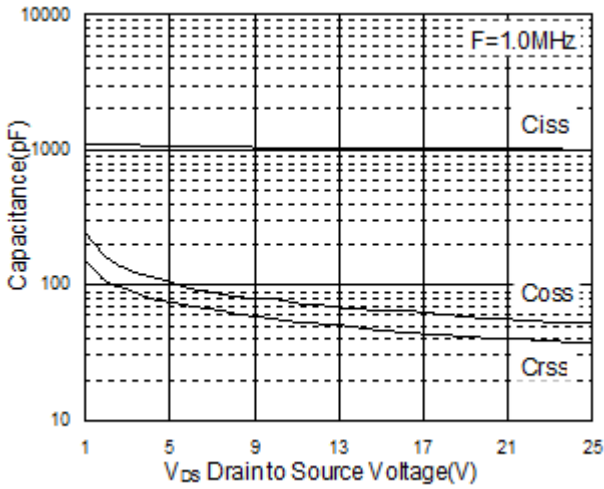


Fig.7 Capacitance

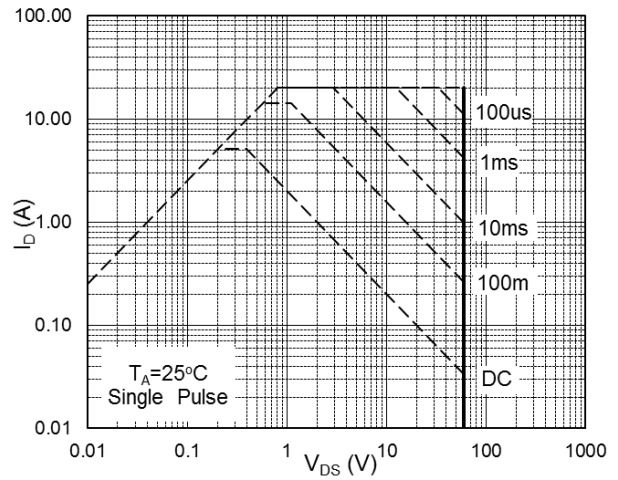


Fig.8 Safe Operating Area

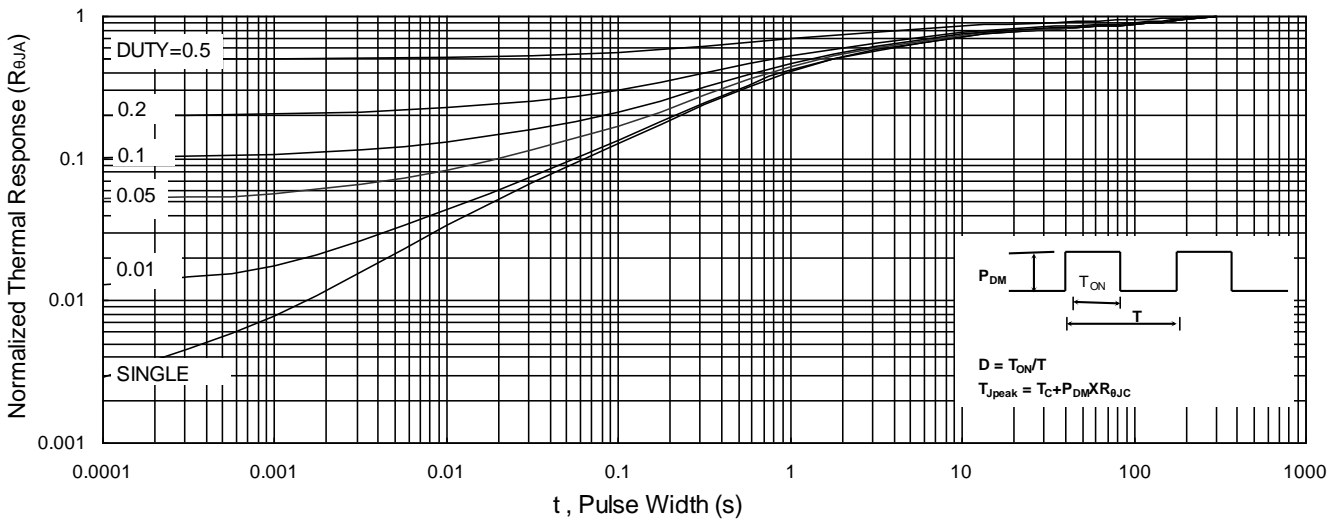


Fig.9 Normalized Maximum Transient Thermal Impedance

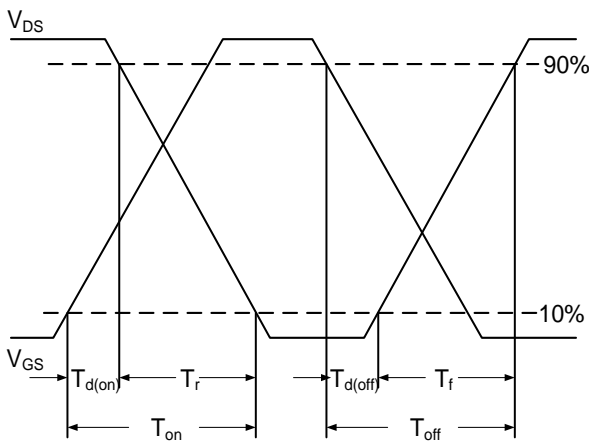


Fig.10 Switching Time Waveform

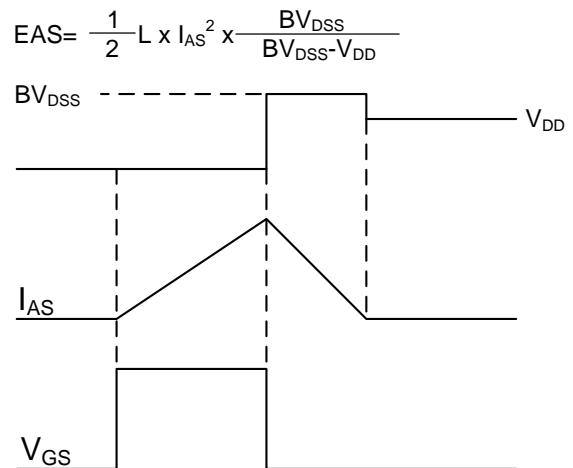


Fig.11 Unclamped Inductive Waveform

N-Ch and P-Ch Fast Switching MOSFET

$V_{DS}=60V, I_D=5.0A, R_{DS(ON)}=52m\Omega$

$V_{DS}=-60V, I_D=-3.8A, R_{DS(ON)}=100m\Omega$

## P-Channel Typical Characteristics

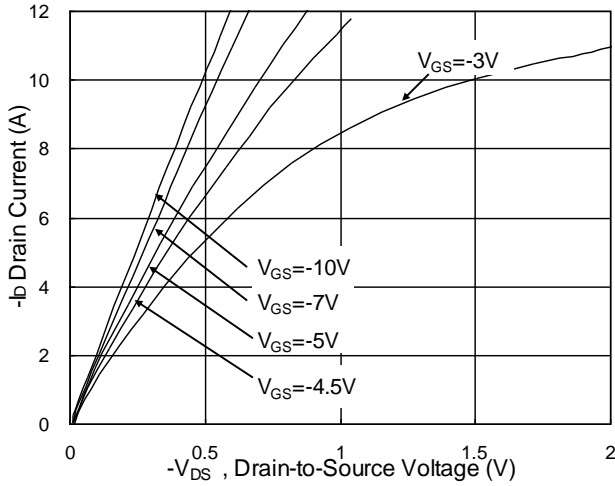


Fig.1 Typical Output Characteristics

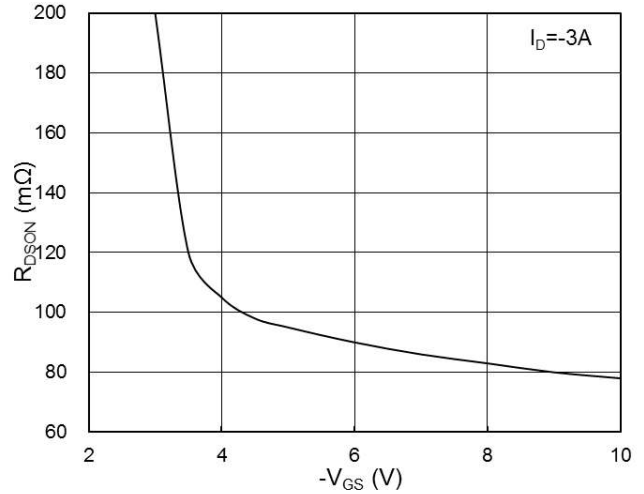


Fig.2 On-Resistance vs. G-S Voltage

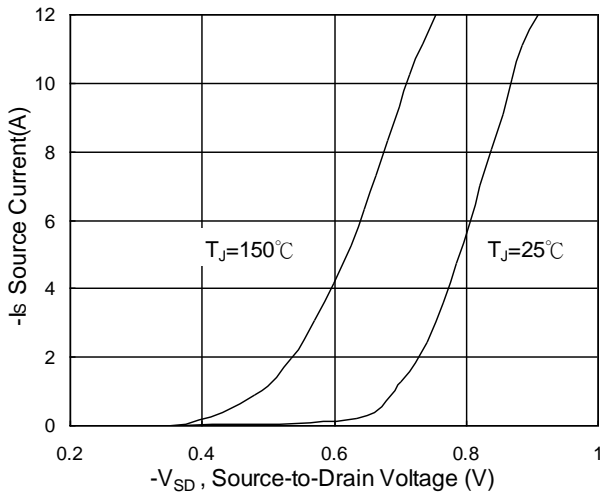


Fig.3 Source Drain Forward Characteristics

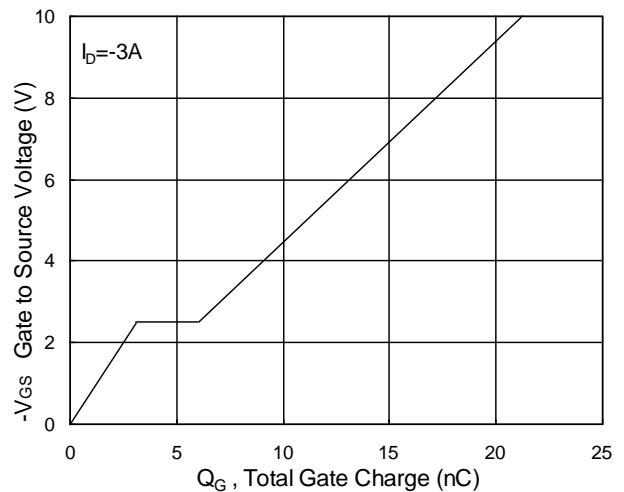


Fig.4 Gate-Charge Characteristics

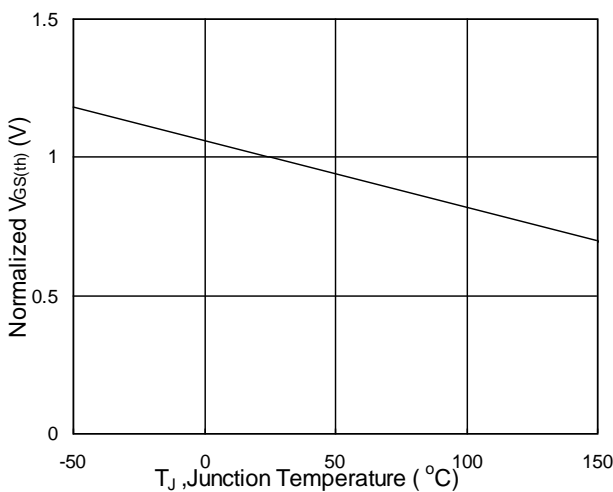


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

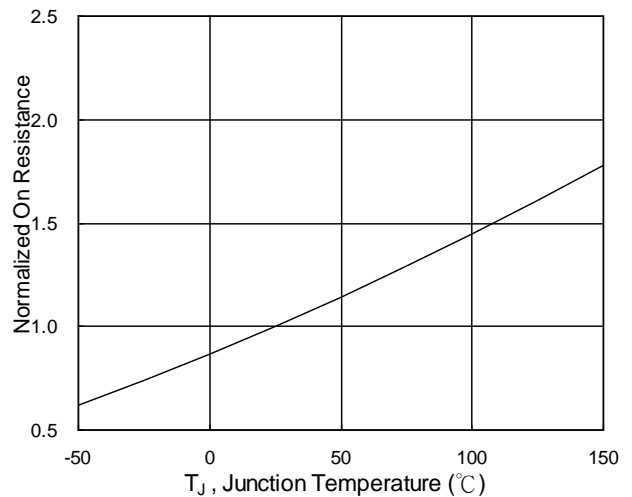


Fig.6 Normalized  $R_{DS(ON)}$  vs.  $T_J$

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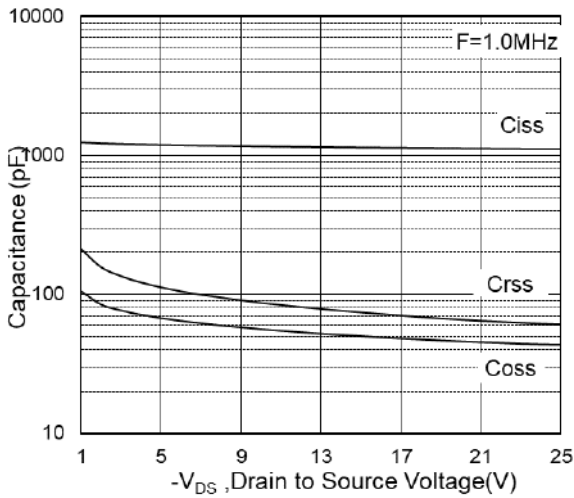


Fig.7 Capacitance

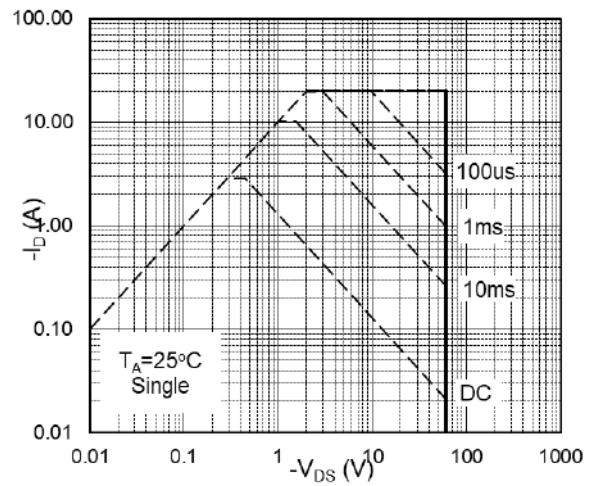


Fig.8 Safe Operating Area

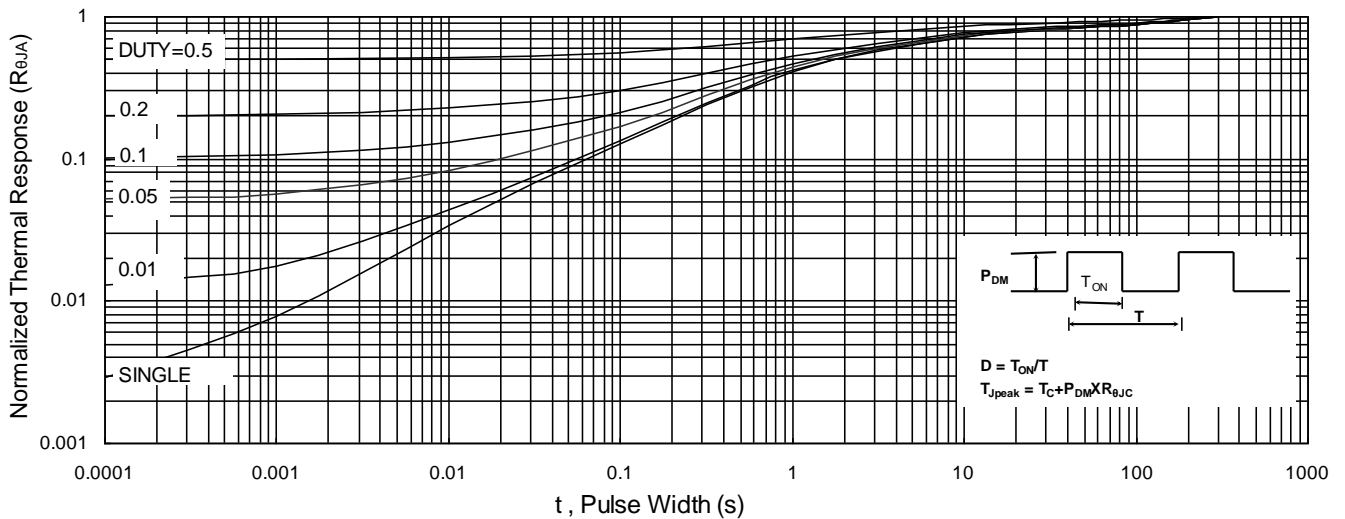


Fig.9 Normalized Maximum Transient Thermal Impedance

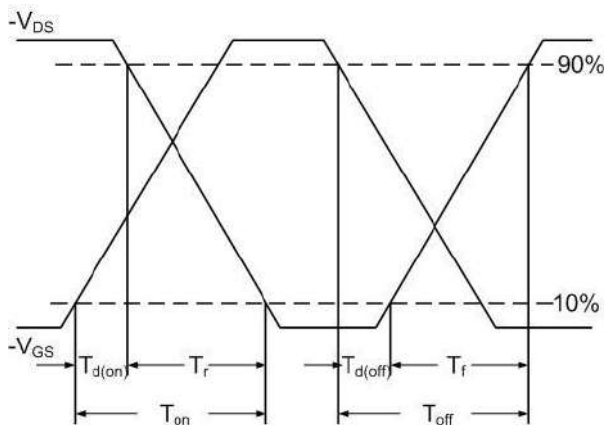


Fig.10 Switching Time Waveform

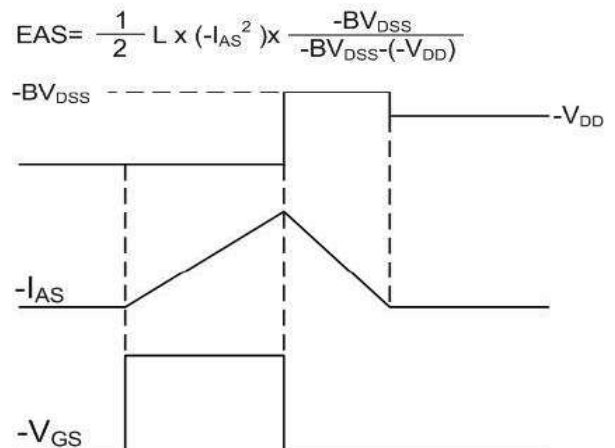


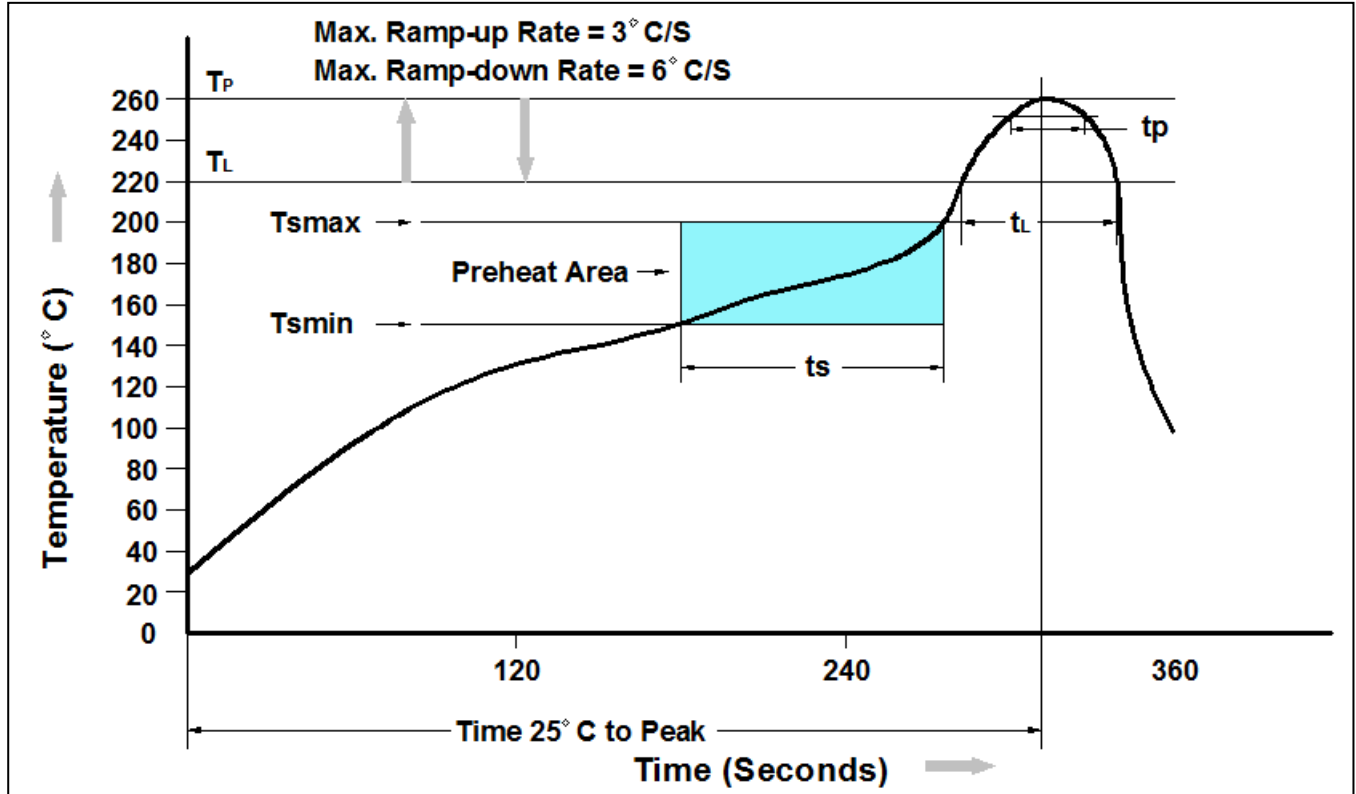
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## ➤ Recommnd IR Reflow Soldering Thermal Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	150°C
Temperature Max. (T <sub>smax</sub> )	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds
Average Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

## ➤ Ordering Information

Part Number	Description	Quantity
PAC69TJ03J	SOP-8 Reel	2500 pcs

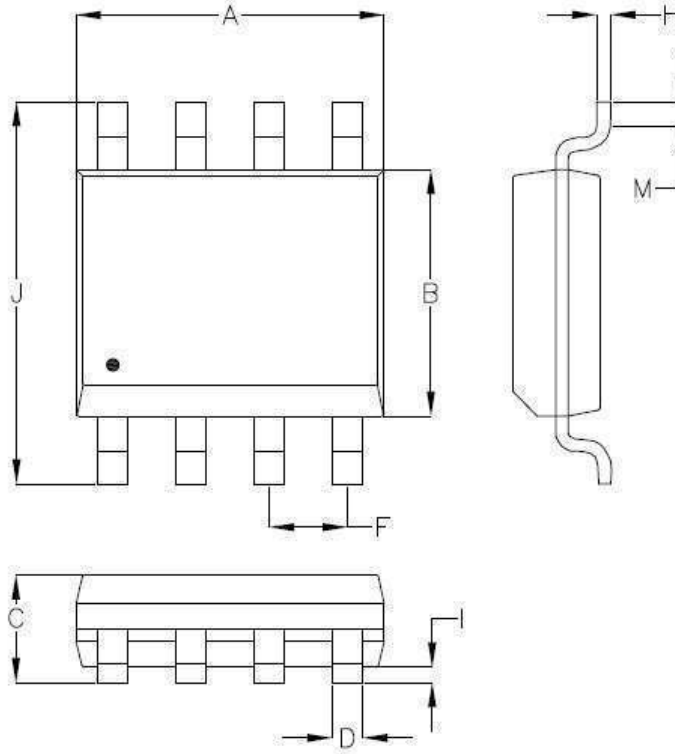


N-Ch and P-Ch Fast Switching MOSFET

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$V_{DS}=-60V$ ,  $I_D=-3.8A$ ,  $R_{DS(ON)}=100m\Omega$

➤ Package Information (SOP-8)



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.700	5.150	0.185	0.203
B	3.700	4.100	0.146	0.161
C	1.23	1.753	0.048	0.069
D	0.310	0.510	0.012	0.020
F	1.070	1.470	0.042	0.058
H	0.160	0.254	0.006	0.010
I	0.050	0.254	0.002	0.010
J	5.750	6.250	0.226	0.246
M	0.400	1.270	0.016	0.050

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